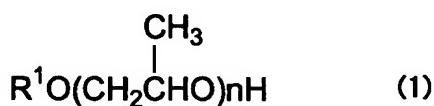


What we claim is :

1. A cleaning agent for removing the solder flux which sets a content of benzyl alcohol to a value which falls within a range of 70 to 99.9 weight% and a content of amino alcohol to a value which falls within a range of 0.1 to 30 weight% when a content of a glycol compound is below 1 weight% with respect to a total amount of the cleaning agent for removing the solder flux, and sets a content of benzyl alcohol to a value which falls within a range of 15 to 99 weight% and a content of amino alcohol to a value which falls within a range of 0.1 to 30 weight% when a content of the glycol compound falls within a range of 1 to 40 weight% with respect to a total amount of the cleaning agent for removing the solder flux.

2. The cleaning agent for removing the solder flux according to claim 1, wherein when the cleaning agent for removing the solder flux contains a surfactant, a content of the surfactant is set to a value of below 0.1 weight% with respect to the total amount of the cleaning agent for removing the solder flux.

3. The cleaning agent for removing the solder flux according to claim 1 or claim 2, wherein the glycol compound is glycol ether compound expressed by a following general formula (1).



(In the general formula (1), R^1 is an alkyl group having 1 to

8 carbons and the repetition number n is an integer from 1 to 3.)

4. The cleaning agent for removing the solder flux according to any one of claims 1 to 3, wherein the cleaning agent further includes a phenol-based antioxidant by an amount which falls within a range of 0.01 to 10 weight% with respect to a total amount of the cleaning agent for removing the solder flux.

5. The cleaning agent for removing the solder flux according to any one of claims 1 to 4, wherein a solubility parameter is set to a value which falls within a range of 10 to 15.

6. The cleaning agent for removing the solder flux according to any one of claims 1 to 5, wherein the electric conductivity is set to a value which falls within a range of 0.5 to 20 $\mu\text{S}/\text{cm}$.

7. The cleaning agent for removing the solder flux according to any one of claims 1 to 6, wherein the difference ($\tan\delta$ at 97%RH - $\tan\delta$ at 54%RH) between a dielectric loss measured under an atmosphere of relative humidity of 97% ($\tan\delta$ at 97%RH) using a JIS 2-type comb-type electrode attached substrate and the dielectric loss measured under the atmosphere of relative humidity of 54% ($\tan\delta$ at 54%RH) using the JIS 2-type comb-type electrode attached substrate is set to a value which is 0.03 or less.

8. The cleaning agent for removing the solder flux according to any one of claims 1 to 7, wherein an object to be

cleaned is a solder flux which is formed of either one of a lead-free solder flux or a high-melting-point solder flux containing rosin as a main component to which at least one compound selected from a group consisting of an organic acid salt, a glycidyl ether compound, an oxyacid compound, a carboxylic acid compound, an anilide compound and a thermosetting resin is added.

9. A method for cleaning the solder flux comprising:
a step in which an object to be cleaned to which a solder flux is attached is cleaned using a cleaning agent for removing the solder flux which sets a content of benzyl alcohol to a value which falls within a range of 70 to 99.9 weight% and a content of amino alcohol to a value which falls within a range of 0.1 to 30 weight% when a content of a glycol compound is below 1 weight% with respect to a total amount of the cleaning agent for removing the solder flux, and sets a content of benzyl alcohol to a value which falls within a range of 15 to 99 weight% and a content of amino alcohol to a value which falls within a range of 0.1 to 30 weight% when a content of the glycol compound falls within a range of 1 to 40 weight% with respect to the total amount of the cleaning agent for removing the solder flux; and
a rinsing step which rinses the object to be cleaned using an alcoholic solvent.

10. The method for cleaning the solder flux according to claim 9, wherein the concentration of benzyl alcohol in the rinse solution in the rinsing step is set to 30 weight% or less.

11. The method for cleaning the solder flux according to claim 9 or 10, wherein the solder flux is either a lead-free

solder flux or a high-melting-point solder flux containing rosin as a main component.

12. The method for cleaning the solder flux according to any one of claims 9 to 11, wherein an object to be cleaned to which the solder flux is adhered is cleaned under conditions of 10 to 90 °C and 0.5 to 30 minutes using a cleaning agent for removing the solder flux.